



May 12, 2005

To: William Peverill (Secretary EIA CE2.0)

From: Jeff Toran (Deputy Technical Advisor – IEC TC48)

C: Carl Fritz (Assistant Secretary IEC SC48B)

RE: IEC Connector Standards Meetings – report for EIA CE2.0

The IEC TC48 Connector & Mechanical Enclosure Standards meetings were held April 2005. The items (briefly) captured below relate to the Connector sub-committee activity and some general areas. There are additional connector standards under development and several in the Mechanical Enclosure's group. If you would like more information please contact me.

Countries participating:

France, Germany, Italy, Japan, Netherlands, United Kingdom and USA.

**Projects under preparation:**

1. USB + Power (both style A and B as separate standards). Anticipated publication, 2Q06 – delayed due to drawing preparation. Formatted: Bullets and Numbering
2. 4 position IEEE 1394 connector for standardization. Anticipated publication 1Q06
3. Infiniband I/O cable connector. Anticipated publication 4Q06.
4. RJ45 Industrial Ethernet standard. Anticipated publication 1Q06
5. Category 5 & 6 Connector standards. Separate standards are being prepared. The Cat 5 standard was published January 2005. Anticipated publication for the Cat 6 document is 4Q05.
6. Revised Connector qualification test schedules. Anticipated publication 3Q06.
7. Eye pattern and jitter test method, (60512-25-6 when published). Published. Formatted: Bullets and Numbering
8. VSWR, Impedance, reflection coefficient test method, (60512-25-7 when published). Published.
9. Numerous (over 30) of published 60512 series test methods are being revised/modernized. Publication will occur between 2Q01 through 4Q07

## Attachment No. 8

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### Other items of note

1. A sister IEC committee (TC91) is drafting a 'resistance to soldering heat test method, (for 'lead-free' products) for surface mount devices. Will be published as IEC 60068-2-058, Environmental testing - Part: 2-58: Tests - Test Td - Test methods for solderability resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD). Anticipated publication is 3-4Q04.
2. TC91 is also drafting a whisker test method standard that is very similar to the current version of the iNEMI whisker test method document. The IEC standard will probably be published by 1Q06.
3. A task group has been formed an informal to develop/identify a connector for IEC standardization suitable for Category 8 performance and above for telecommunications usage. A standard is being prepared and will be published in 4Q06.

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### Upcoming Meetings

- 1) October 14-21, 2005 – Hosted by South Africa